

Title (en)
METHOD FOR PRODUCING AN ELECTRONIC MODULE HAVING AN INTERLOCKINGLY CONNECTED HOUSING PART ELEMENT

Title (de)
VERFAHREN ZUM HERSTELLEN EINES ELEKTRONIKMODULS MIT FORMSCHLÜSSIG ANGESCHLOSSENEM GEHÄUSETEILELEMENT

Title (fr)
PROCÉDÉ PERMETTANT DE FABRIQUER UN MODULE ÉLECTRONIQUE POURVU D'UN ÉLÉMENT DE PARTIE DE BOÎTIER RACCORDÉ PAR COOPÉRATION DE FORMES

Publication
EP 3084272 A1 20161026 (DE)

Application
EP 14793549 A 20141104

Priority
• DE 102013226150 A 20131217
• EP 2014073684 W 20141104

Abstract (en)
[origin: WO2015090711A1] The invention relates to a method for producing an electronic module, wherein a circuit board element (1) is provided and a housing part element (15) is arranged on the circuit board element (1). The housing part element (15) is first separately produced and prepared. The housing part element (15) is formed by a material that can be reversibly plasticised, for example a thermoplastic such as polyamide. At least one portion (18) of a surface of the housing part element (15) is then reversibly plasticised, for example by means of local heating, in particular by irradiating with light. The housing part element (15) is then arranged on the circuit board element (1) by joining the plasticised portion of the surface of the housing part element to a microstructured portion (7) of the circuit board element and subsequently hardening the plasticised portion (18). Thus, an interlocking and hermetically sealed connection is formed between the housing part element (15) and the circuit board element (1).

IPC 8 full level
F16H 61/00 (2006.01); **B29C 65/16** (2006.01); **G01P 1/02** (2006.01); **H05K 3/00** (2006.01); **H05K 5/00** (2006.01)

CPC (source: EP KR US)
B29C 65/1432 (2013.01 - US); **B29C 65/1632** (2013.01 - EP US); **B29C 65/1635** (2013.01 - EP KR US); **B29C 65/168** (2013.01 - EP KR US); **B29C 65/606** (2013.01 - EP US); **B29C 65/72** (2013.01 - EP US); **B29C 66/112** (2013.01 - EP US); **B29C 66/131** (2013.01 - EP KR US); **B29C 66/30322** (2013.01 - EP US); **B29C 66/322** (2013.01 - EP US); **B29C 66/53461** (2013.01 - EP US); **B29C 66/71** (2013.01 - KR); **B29C 66/712** (2013.01 - US); **B29C 66/7212** (2013.01 - EP US); **B29C 66/73161** (2013.01 - EP US); **B29C 66/7392** (2013.01 - EP KR US); **B29C 66/7394** (2013.01 - EP US); **F16H 61/0006** (2013.01 - EP KR US); **H01L 24/48** (2013.01 - KR); **H01L 24/49** (2013.01 - KR); **H05K 3/0026** (2013.01 - US); **H05K 3/0032** (2013.01 - KR); **H05K 3/284** (2013.01 - EP KR US); **H05K 3/303** (2013.01 - US); **H05K 5/0082** (2013.01 - EP KR US); **B29C 66/71** (2013.01 - EP US); **B29C 66/919** (2013.01 - EP US); **B29K 2309/08** (2013.01 - US); **B29K 2663/00** (2013.01 - US); **B29K 2677/00** (2013.01 - US); **B29L 2031/3481** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/49** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/16151** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **H01L 2924/19105** (2013.01 - EP US); **H01L 2924/19107** (2013.01 - EP US); **H05K 3/0032** (2013.01 - EP US); **H05K 2201/2018** (2013.01 - EP US); **H05K 2201/2072** (2013.01 - EP US)

Citation (search report)
See references of WO 2015090711A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
DE 102013226150 A1 20150618; CN 105917145 A 20160831; EP 3084272 A1 20161026; KR 20160099577 A 20160822; US 2016381817 A1 20161229; WO 2015090711 A1 20150625

DOCDB simple family (application)
DE 102013226150 A 20131217; CN 201480068598 A 20141104; EP 14793549 A 20141104; EP 2014073684 W 20141104; KR 20167016089 A 20141104; US 201415105997 A 20141104